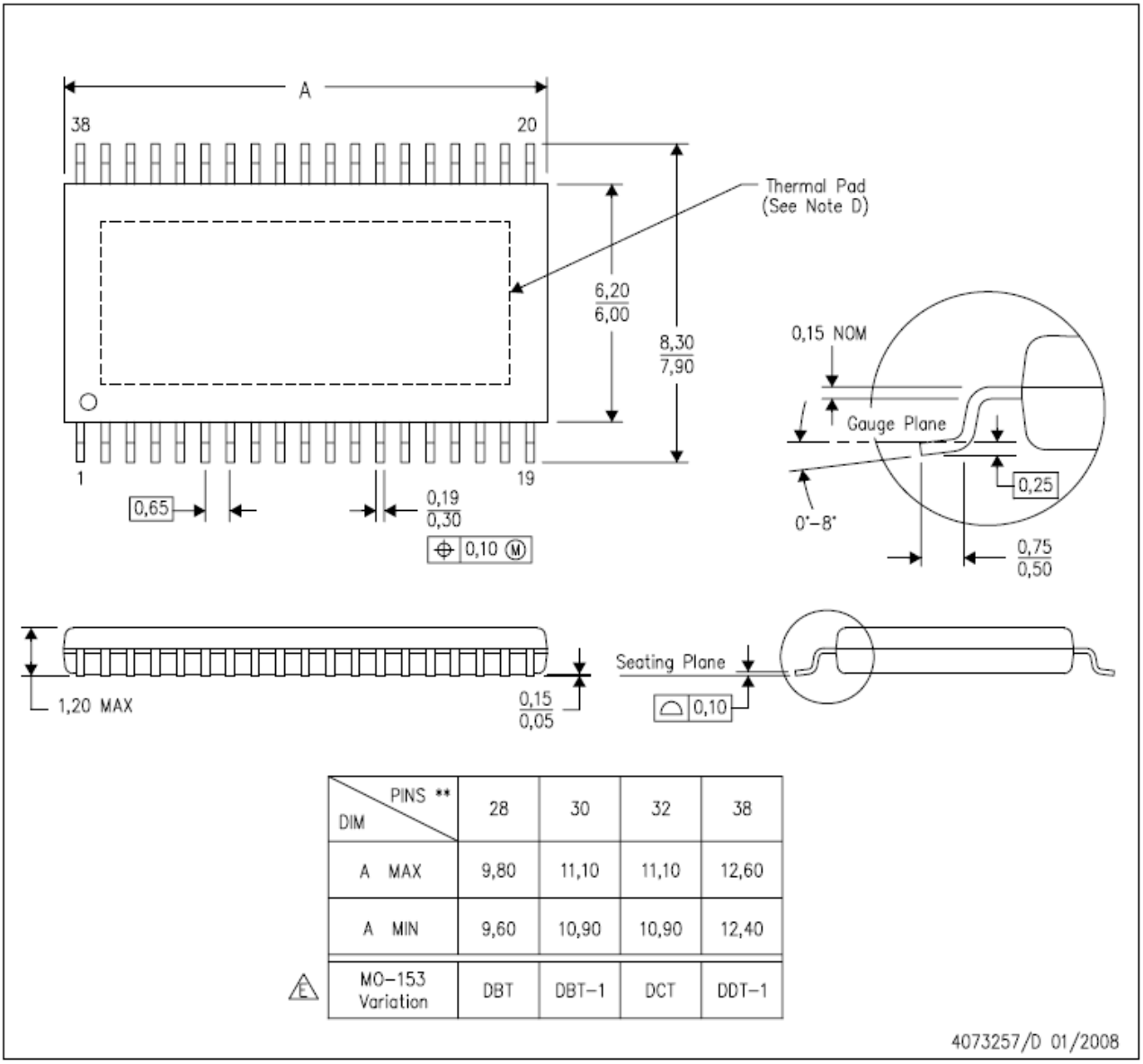
DAP (R–PDSO–G**) PowerPAD™ PLASTIC SMALL–OUTLINE PACKAGE

38 PINS SHOWN



DIM \ PINS **	28	30	32	38
A MAX	9,80	11,10	11,10	12,60
A MIN	9,60	10,90	10,90	12,40
MO–153 Variation (E)	DBT	DBT–1	DCT	DDT–1

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. Falls within JEDEC MO–153, except 30 pin body length.